

Title (en)

COOLING BODY FOR SEMICONDUCTOR LIGHTING DEVICE WITH PLASTICS PARTS

Title (de)

KÜHLKÖRPER FÜR HALBLEITERLEUCHTVORRICHTUNG MIT KUNSTSTOFFTEILEN

Title (fr)

CORPS DE REFROIDISSEMENT DE DISPOSITIF D'ÉCLAIRAGE À SEMI-CONDUCTEUR COMPRENANT DES PARTIES EN MATIÈRE PLASTIQUE

Publication

**EP 2783153 A1 20141001 (DE)**

Application

**EP 12784475 A 20121010**

Priority

- DE 102011086789 A 20111122
- EP 2012070023 W 20121010

Abstract (en)

[origin: WO2013075880A1] The cooling body (11) is provided for a semiconductor lighting device (H), wherein the cooling body (11) comprises at least: a first plastics part (12), which has a receptacle space (13) open at the rear side; and a second plastics part (14), which is connected to the first plastics part (12) at the front side (15) thereof and is provided for arranging at least one semiconductor light source (22), wherein the first plastics part (12) has a lower thermal conductivity than the second plastics part (14) and at least one insert (18) having a higher thermal conductivity than the second plastics part (14) is present in the cooling body. A semiconductor lighting device comprises such a cooling body (11).

IPC 8 full level

**F21V 29/87** (2015.01); **F21K 99/00** (2016.01)

CPC (source: EP US)

**F21K 9/23** (2016.07 - EP US); **F21V 29/87** (2015.01 - EP US); **F21Y 2115/10** (2016.07 - EP US)

Citation (search report)

See references of WO 2013075880A1

Cited by

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DOCDB simple family (publication)

**DE 102011086789 A1 20130523**; EP 2783153 A1 20141001; EP 2783153 B1 20160824; WO 2013075880 A1 20130530

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